

ABSTRACT OF THE DISCLOSURE

A frame attaching process is described. The frame attaching process is adapted for attaching a transparent substrate to an active area of a chip using a frame, wherein the active area of the chip has a functional area. In the frame attaching process, the frame can be formed on the attaching surface of the transparent substrate or on the active area of the chip. Then, the attaching surface of the transparent substrate is attached to the active area of the chip using the frame under a negative pressure. Finally, the frame is solidified. Therefore, in the frame attaching process, the possibility of frame cracking can be reduced and the yield of the frame attaching process can be improved.